HALOGEN

FREE

GREEN (5-2008)



Vishay Vitramon

Surface Mount Multilayer Ceramic Chip Capacitors for High Temperature Applications Up to 150 °C



FEATURES

- Specialty: high temperature applications
- High operating temperature dielectric: 150 °C
- Maintains capacitance at high temperature for frequency stability
- · Wet build process
- Reliable Noble Metal Electrode (NME) system
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

APPLICATIONS

• High temperature modules

ELECTRICAL SPECIFICATIONS

Note

• Electrical characteristics at +25 °C unless otherwise specified.

Operating Temperature: -55 °C to +150 °C

Capacitance Range: 330 pF to 220 nF

Voltage Range: 25 V_{DC} to 100 V_{DC}

Temperature Coefficient of Capacitance (TCC):

± 15 % from -55 °C to +150 °C

Dissipation Factor (DF):

25 V ratings: 3.5 % maximum at 1.0 V_{RMS} and 1 kHz > 25 V ratings: 2.5 % maximum at 1.0 V_{RMS} and 1 kHz

Aging Rate: 1 % maximum per decade

Insulation Resistance (IR):

at +25 °C and rated voltage 100 000 M Ω minimum or 1000 $\Omega F,$ whichever is less

at +125 °C and rated voltage 10 000 M Ω minimum or

100 Ω F, whichever is less

Dielectric Strength Test:

performed per method 103 of EIA-198-2-E Applied test voltage:

≤ 100 V_{DC}-rated: 250 % of rated voltage



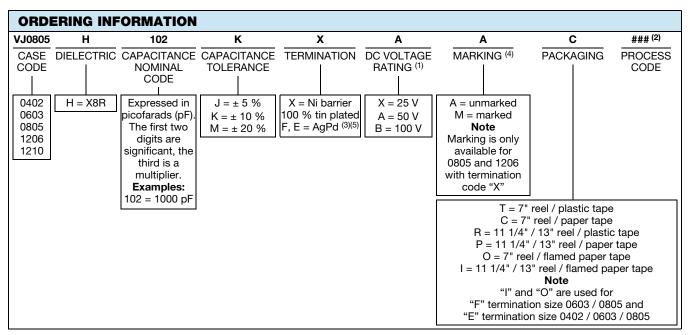
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QUICK REFERENCE DATA							
DIELECTRIC	CASE	MAXIMUM VOLTAGE	CAPACITANCE				
		(V)	MINIMUM	MAXIMUM			
X8R	0402	100	330 pF	6.8 nF			
	0603	100	470 pF	33 nF			
	0805	100	470 pF	100 nF			
	1206	50	1.0 nF	220 nF			
	1210	50	10 nF	220 nF			

Note

· Detail ratings see "Selection Chart"



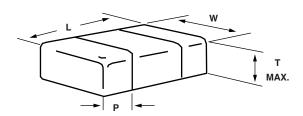
Notes

- (1) DC voltage rating should not be exceeded in application. Other application factors may affect the MLCC performance. Consult for questions: mlcc@vishay.com
- Process code may be added with up to three digits, used to control non-standard products and requirements
- (3) Termination code "E" for conductive epoxy assembly
- (4) Marking in reference to EIA198, see www.vishay.com/doc?45028
- (5) Termination code "F" not available for 0402, 0603 100 V, 0805 100 V

ENVIRONMENTAL STATUS								
TERMINATION CODE	TERMINATION DESCRIPTION	RoHS COMPLIANT	VISHAY GREEN					
Х	Ni barrier 100 % tin plated matte finish	Yes	Yes					
E	AgPd	Yes	Yes					
F	AgPd	Yes	No					

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DIMENSIONS in inches (millimeters)



CASE	STYLE	LENGTH	WIDTH	MAXIMUM THICKNESS	TERMINATION (P)		
CODE		(L)	(W)	(т)	MINIMUM	MAXIMUM	
0402	VJ0402	0.040 + 0.004/- 0.002 (1.00 + 0.10/- 0.05)	0.020 + 0.004/- 0.002 (0.50 + 0.10/- 0.05)	0.024 (0.60)	0.004 (0.10)	0.016 (0.41)	
0603	VJ0603	0.063 ± 0.006 (1.60 ± 0.15)	0.031 ± 0.006 (0.80 ± 0.15)	0.036 (0.92)	0.012 (0.30)	0.022 (0.55)	
0805	VJ0805	0.079 ± 0.008 (2.00 ± 0.20)	0.049 ± 0.008 (1.25 ± 0.20)	0.057 (1.45)	0.010 (0.25)	0.030 (0.76)	
1206	VJ1206	0.126 ± 0.010 (3.20 ± 0.25)	0.063 ± 0.010 (1.60 ± 0.25)	0.067 (1.70)	0.010 (0.25)	0.030 (0.76)	
1210	VJ1210	0.126 ± 0.010 (3.20 ± 0.25)	0.098 ± 0.010 (2.50 ± 0.25)	0.067 (1.70)	0.010 (0.25)	0.030 (0.76)	





SELECTIO	ON CHART													
DIELECTRIC								X8R						
STYLE						VJ1206 ⁽¹⁾		VJ1210 ⁽¹⁾						
CASE CODE			0402			0603		0805 1206		206	1210			
VOLTAGE (V	DC)	25	50	100	25	50	100	25	50	100			25	50
VOLTAGE CO		Х	Α	В	Х	Α	В	Х	Α	В	Х	Α	Х	Α
CAP. CODE	CAP.													
331	330 pF	••	••	••										
391	390 pF	••	••	••										
471	470 pF	••	••	••		••	••	••	••	••				
561	560 pF	••	••	••		••	••	••	••	••				
681	680 pF	••	••	••	••	••	••	••	••	••				
821	820 pF	••	••	••	••	••	••	••	••	••				
102	1.0 nF	••	••	••	••	••	••	••	••	••	•	•		
122	1.2 nF	••	••	••	••	••	••	••	••	••	•	•		
152	1.5 nF	••	••		••	••	••	••	••	••	•	•		
182	1.8 nF	••	••		••	••	••	••	••	••	•	•		
222	2.2 nF	••	••		••	••	••	••	••	••	•	•		
272	2.7 nF	••			••	••	••	••	••	••	•	•		
332	3.3 nF	••			••	••	••	••	••	••	•	•		
392	3.9 nF	••			••	••	••	••	••	••	•	•		
472	4.7 nF	••			••	••	••	••	••	••	•	•		
562	5.6 nF	••			••	••		••	••	••	•	•		
682	6.8 nF	••			••	••		••	••	••	•	•		
822	8.2 nF				••	••		••	••	••	•	•		
103	10 nF				••	••		••	••	••	•	•	•	•
123	12 nF				••	••		••	••	••	•	•	•	•
153	15 nF				••	••		••	••	••	•	•	•	•
183	18 nF				••	••		••	••	••	•	•	•	•
223	22 nF				••			••	••	•	•	•	•	•
273	27 nF				••			••	•	•	•	•	•	•
333	33 nF				••			••	•		•	•	•	•
393	39 nF							••	•		•	•	•	•
473	47 nF							•	•		•	•	•	•
563	56 nF							•	•		•	•	•	•
683	68 nF	1						•			•	•	•	•
823	82 nF	1						•			•	•	•	•
104	100 nF							•			•	•	•	•
124	120 nF	1									•	•	•	•
154	150 nF	1									•		•	•
184	180 nF	1									•		•	
224	220 nF	1									•		•	
274	270 nF					1								<u> </u>
334	330 nF					1								<u> </u>
394	390 nF													

Notes

RoHS-compliant

X8R PACKAGING QUANTITIES (1)									
7" REEL QUANTITIES 11 1/4" AND 13" REEL QUAN									
CASE CODE	TAPE SIZE	PACKAG	ING CODE	PACKAGING CODE					
		"C" / "O"	"T"	"P" / "I"	"R"				
0402	8 mm	5000	n/a	10 000	n/a				
0603	8 mm	4000	n/a	10 000	n/a				
0805 ⁽²⁾	8 mm	3000	3000	10 000	10 000				
1206 ⁽²⁾	8 mm	n/a	2500 / 3000	10 000	9000 / 10 000				
1210 ⁽²⁾	8 mm	n/a	2000 / 2500 / 3000	10 000	9000 / 10 000				

Notes

⁽¹⁾ See soldering recommendations within this data book, or visit www.vishay.com/doc?45034

[•] Plastic tape, •• Paper tape

⁽¹⁾ Reference: EIA standard RS481 - "Taping of Surface Mount Components for Automatic Placement"

 $^{^{(2)}}$ Packaging "C" / "P" / "O" / "I" and "T" / "R" or lower quantities can depend from product thickness

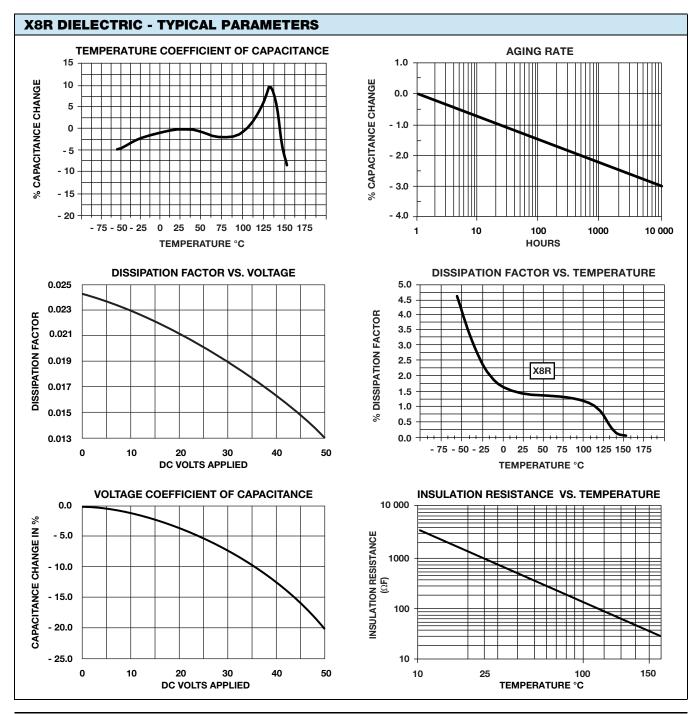


STORAGE AND HANDLING CONDITIONS

- (1) Store the components at 5 $^{\circ}$ C to 40 $^{\circ}$ C ambient temperature and \leq 70 % relative humidity conditions.
- (2) The product is recommended to be used within a time-frame of 2 years after shipment. Check solderability in case extended shelf life beyond the expiry date is needed.

Precautions:

- a. Do not store products in an environment containing corrosive elements, especially where chloride gas, sulfide gas, acid, alkali, salt or the like are present. This may cause corrosion or oxidization of the terminations, which can easily lead to poor soldering.
- b. Store products on the shelf and avoid exposure to moisture or dust.
- c. Do not expose products to excessive shock, vibration, direct sunlight and so on.

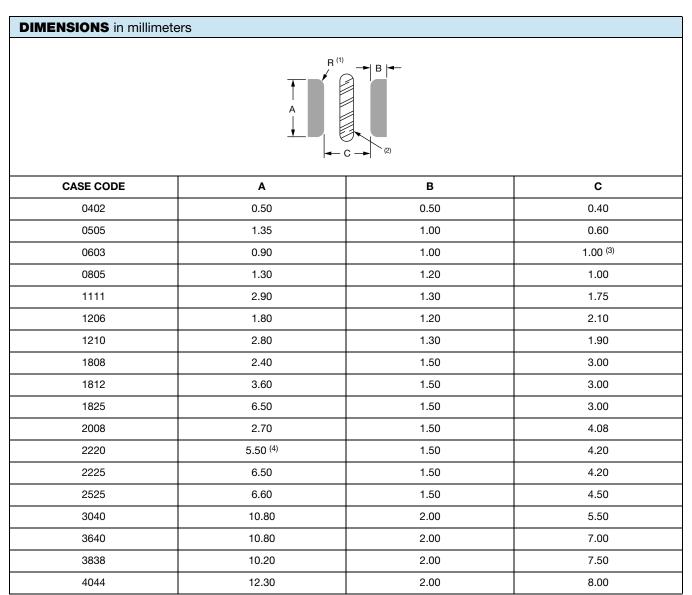




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Solder Pad Dimensions for Vishay Surface-Mount Multilayer Ceramic Chip Capacitors



Notes

⁽¹⁾ For safety capacitors and voltages above 3000 V, corner rounding (R) of 0.5 mm is recommended to suppress arcing

⁽²⁾ Add a 1 mm slot in PCB between pads to allow cleaning and coating under MLCC

⁽³⁾ For VJ HiFREQ Series, this dimension is 0.6 mm

⁽⁴⁾ For safety capacitors, the A dimension should be 5.80 mm

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Guidelines for MLCC Solder Pads and PCBs

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PRINTED CIRCUIT BOARD PCB DESIGN CONSIDERATIONS FOR HIGH VOLTAGE SURFACE-MOUNT MLCCS

Special assembly process and design considerations should be employed for today's high voltage rating MLCCs. As case sizes remain the same and voltage ratings increase, MLCC manufacturers must design, evaluate, and qualify their capacitors using methods that reduce the occurrence of corona discharge and arcover events. To meet similar capability in high voltage applications, users should employ similar cautionary design and assembly methods.

MLCC PAD LAYOUT

A capacitor's arcover inception point can degrade due to factors such as the MLCC termination, PCB pad design, PCB cleanliness, solder flux residue, surface contamination / deposits and environmental conditions. PCB pads and their design affect the air gap distance between the opposing polarities of the MLCC termination. For voltage rating greater than 1500 V_{DC} add a corner radius to the inward facing edge of the MLCC pads and as large a gap as possible between the pads. Too small of a pad gap distance will reduce the capacitor's own arcover inception voltage level. Refer to the Figure and Table Figure 1.0, MLCC Pad Layout and Table 1.0, Vishay MLCC Solder Pad Dimensions for the recommended MLCC solder pad dimensions.

SLOT OR TRENCH BETWEEN PADS

PCB assembly can deposit dust, trap solder balls, or flux residue underneath the capacitors. These contaminants will reduce conductive clearances and the arcover inception level. Assembly methods must include a final PCB cleaning process. A slot or trench can be cut into the PCB in between the pads to allow cleaners to penetrate underneath the MLCC. The slot will also allow conformal or epoxy coatings to flow underneath the MLCC and build an insulative barrier between pads. Refer to Figure 1.0 MLCC Pad Layout for slot reference location.

COATING PRINTED CIRCUIT BOARD

Coating a printed circuit board with materials such as acrylic, silicone and urethane resins provide a protective dielectric barrier that is non-conductive and will enhance the resistance to arcing. Various processes exist which include dipping, brushing, and spaying. Optimal performance will come from coating the MLCC on all sides, top and bottom. The PCB slot in between the pads should extend slightly beyond the width of the MLCC. Refer to Figure 1.0 MLCC Pad Layout for slot reference location.



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